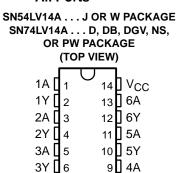
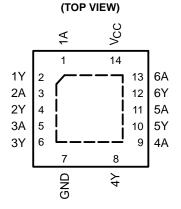
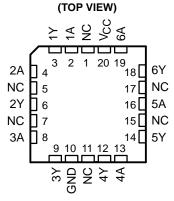
- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 10 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- Support Mixed-Mode Voltage Operation on All Ports
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



GND



SN74LV14A . . . RGY PACKAGE



SN54LV14A . . . FK PACKAGE

NC - No internal connection

description/ordering information

8 🛮 4Y

These hex Schmitt-trigger inverters are designed for 2-V to 5.5-V V_{CC} operation.

The 'LV14A devices contain six independent inverters. These devices perform the Boolean function $Y = \overline{A}$.

These devices are fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

ORDERING INFORMATION

TA	PACK	AGET	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QFN – RGY	Tape and reel	SN74LV14ARGYR	LV14A
	SOIC - D	Tube	SN74LV14AD	LV14A
	30IC = D	Tape and reel	SN74LV14ADR	LV 14A
–40°C to 85°C	SOP - NS	Tape and reel	SN74LV14ANSR	74LV14A
	SSOP – DB	Tape and reel	SN74LV14ADBR	LV14A
	TSSOP - PW	Tape and reel	SN74LV14APWR	LV14A
	TVSOP - DGV	Tape and reel	SN74LV14ADGVR	LV14A
	CDIP – J	Tube	SNJ54LV14AJ	SNJ54LV14AJ
–55°C to 125°C	CFP – W	Tube	SNJ54LV14AW	SNJ54LV14AW
	LCCC – FK	Tube	SNJ54LV14AFK	SNJ54LV14AFK

[†]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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FUNCTION TABLE (each inverter)

INPUT A	OUTPUT Y
Н	L
L	Н

logic diagram, each inverter (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance	
or power-off state, V _O (see Note 1)	–0.5 V to 7 V
Output voltage range, VO (see Notes 1 and 2)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V _{CC} or GND	
Package thermal impedance, θ _{JA} (see Note 3): D package	86°C/W
(see Note 3): DB package	96°C/W
(see Note 3): DGV package	127°C/W
(see Note 3): NS package	76°C/W
(see Note 3): PW package	113°C/W
(see Note 4): RGY package	47°C/W
Storage temperature range, T _{stq}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 5.5 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.
- 4. The package thermal impedance is calculated in accordance with JESD 51-5.



recommended operating conditions (see Note 5)

			SN54L	V14A	SN74	LV14A	UNIT
			MIN	MAX	MIN	MAX	UNII
Vcc	Supply voltage		2	5.5	2	5.5	V
		V _{CC} = 2 V	1.5		1.5		
\/	High level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		V
VIH	High-level input voltage	V _{CC} = 3 V to 3.6 V	V _{CC} × 0.7		$V_{CC} \times 0.7$		V
		V _{CC} = 4.5 V to 5.5 V	V _{CC} × 0.7		$V_{CC} \times 0.7$		
		V _{CC} = 2 V		0.5		0.5	
\/	Low lovel input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	\	/CC×0.3		V _{CC} ×0.3	V
VIL	Low-level input voltage	$V_{CC} = 3 V \text{ to } 3.6 V$	\	/CC×0.3		V _{CC} ×0.3	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$,	$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	
٧ _I	Input voltage		0	5.5	0	5.5	V
٧o	Output voltage		0 0	Vcc	0	VCC	٧
		V _{CC} = 2 V	200	-50		-50	μΑ
	High lovel output ourrent	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-2		-2	
ЮН	High-level output current	$V_{CC} = 3 V \text{ to } 3.6 V$		-6		-6	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-12		-12	
		V _{CC} = 2 V		50		50	μΑ
l au	Low lovel output ourrent	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2		2	
lOL	Low-level output current	$V_{CC} = 3 V \text{ to } 3.6 V$		6		6	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		12		12	
TA	Operating free-air temperature		- 55	125	-40	85	°C

NOTE 5: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEGT CONDITIONS		SN54LV14	A	SN7	4LV14	A			
PARAMETER	TEST CONDITIONS	vcc	MIN TYP	MAX	MIN	TYP	MAX	UNIT		
V _{T+}		2.5 V		1.75			1.75			
Positive-going		3.3 V		2.31			2.31	V		
threshold		5 V		3.5			3.5			
V _T _		2.5 V	0.75		0.75					
Negative-going		3.3 V	0.99		0.99			V		
threshold		5 V	1.5		1.5					
		2.5 V	0.25	1	0.25		1			
ΔV_T Hysteresis ($V_{T+} - V_{T-}$)		3.3 V	0.33	1.32	0.33		1.32	V		
Trystoresis (V + V =)		5 V	0.5	2	0.5		2			
	I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1		V _{CC} -0.1					
Vari	I _{OH} = -2 mA	2.3 V	2		2			V		
VOH	I _{OH} = -6 mA	3 V	2.48		2.48					
	I _{OH} = -12 mA	4.5 V	3.8		3.8					
	I _{OL} = 50 μA	2 V to 5.5 V	40	0.1			0.1			
\/o	I _{OL} = 2 mA	2.3 V		0.4			0.4	V		
VOL	I _{OL} = 6 mA	3 V		0.44			0.44	v		
	I _{OL} = 12 mA	4.5 V		0.55			0.55			
lį	V _I = V _{CC} or GND	0 V to 5.5 V		±1			±1	μΑ		
lcc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V		20			20	μΑ		
l _{off}	V_I or $V_O = 0$ to 5.5 V	0 V		5			5	μΑ		
C _i	VI = Voc or GND	3.3 V	2.3			2.3		pF		
O _I	$V_I = V_{CC}$ or GND	5 V	2.3			2.3		þΓ		

switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T,	_Δ = 25°C	;	SN54L\	/14A	SN74L	V14A	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
tou	Λ	V	C _L = 15 pF		10.2*	19.7*	√1 */	22*	1	22	20
^t pd	A	1	C _L = 50 pF		13.3	24	Q1	27	1	27	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T,	Վ = 25° C	;	SN54LV1	14A	SN74L	V14A	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
to d	Δ	V	C _L = 15 pF		7.3*	12.8*	1*	15.9*	1	15	20
^t pd	A	1	C _L = 50 pF		9.6	16.3	Q1	19.4	1	18.5	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	LOAD	T,	4 = 25°C	;	SN54LV	14A	SN74L	V14A	UNIT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
t _{n-1}	Λ	V	C _L = 15 pF		5.1*	8.6*	1*	10*	1	10	no
^t pd	A	ī	C _L = 50 pF		6.7	10.6	Q1	12	1	12	ns

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, $V_{CC} = 3.3 \text{ V}$, $C_L = 50 \text{ pF}$, $T_A = 25^{\circ}\text{C}$ (see Note 6)

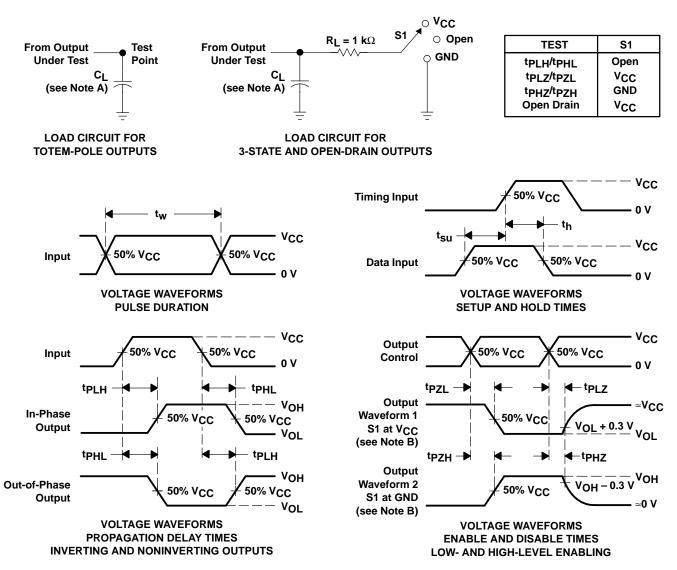
	PARAMETER	SN	UNIT		
	PARAMETER	MIN	TYP	MAX	UNII
VOL(P)	Quiet output, maximum dynamic V _{OL}		0.2	0.8	V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.1	-0.8	V
VOH(V)	Quiet output, minimum dynamic V _{OH}		3.1		V
VIH(D)	High-level dynamic input voltage	2.31			V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

NOTE 6: Characteristics are for surface-mount packages only.

operating characteristics, T_A = 25°C

	PARAMETER			TEST CONDITIONS			UNIT
	C _{pd} Power dissipation capacitance	Power discipation capacitance	$C_1 = 50 pF$	f = 10 MHz	3.3 V	8.8	pF
		Power dissipation capacitance	CL = 50 pr,	1 - 10 101112	5 V	9.6	pr

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \Omega$, $t_f \leq 3$ ns, $t_f \leq 3$ ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. t_{PHL} and t_{PLH} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

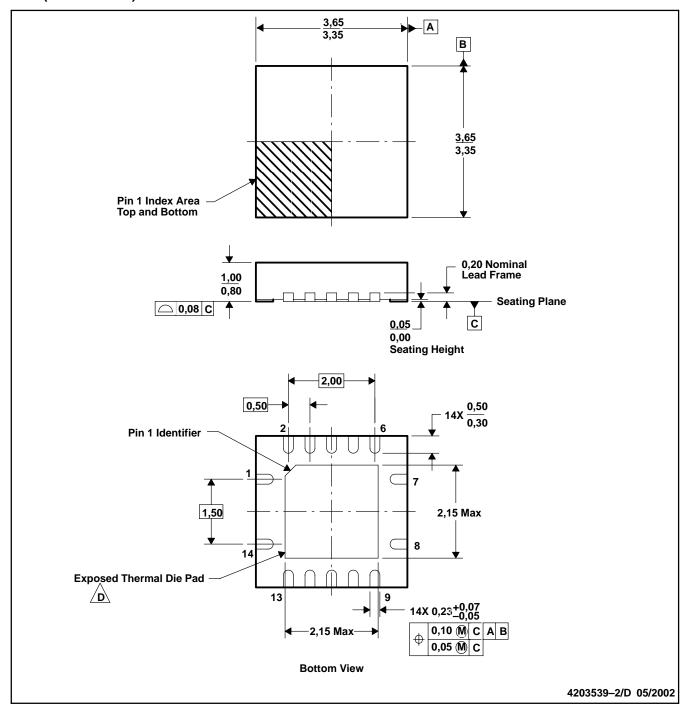
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

RGY (S-PQFP-N14)

PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

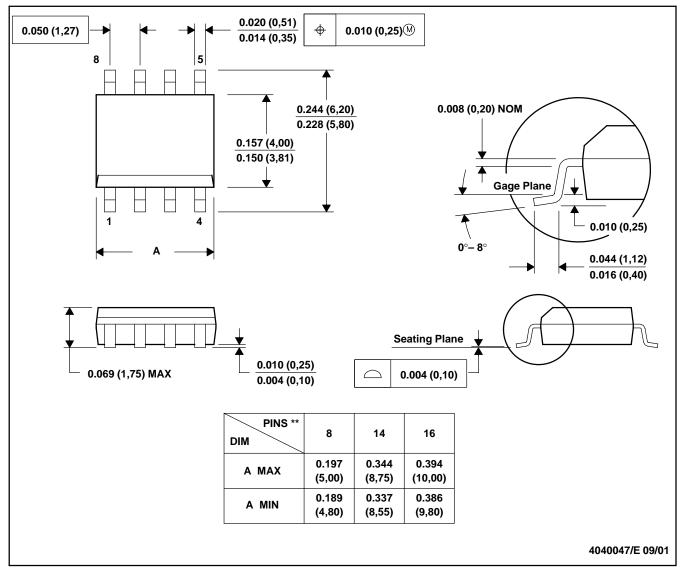
- B. This drawing is subject to change without notice.
- C. QFN (Quad Flatpack No-Lead) Package configuration.
- D. The Package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected ground leads.



D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

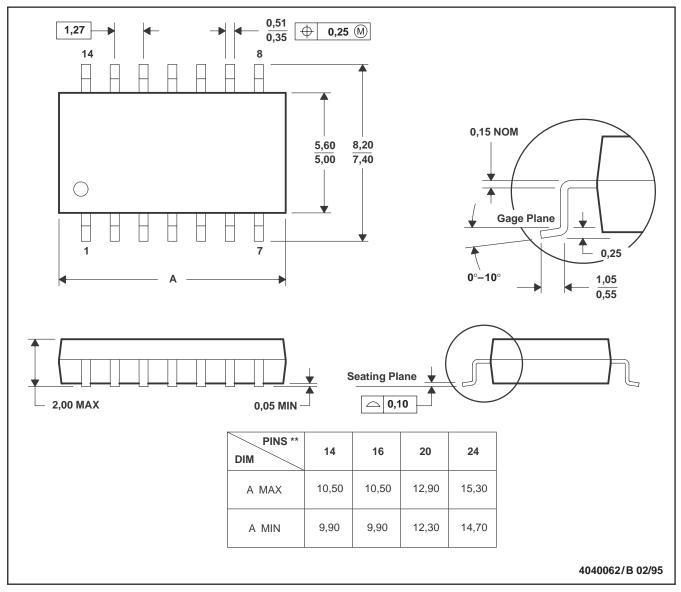
C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

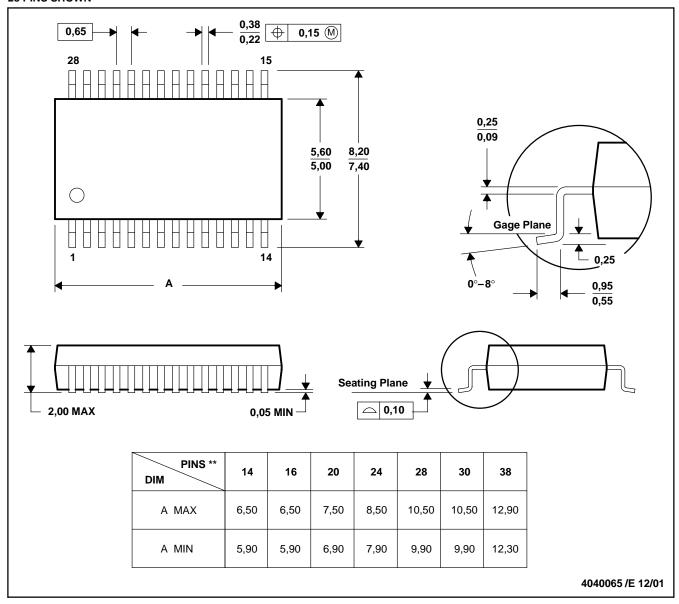
B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

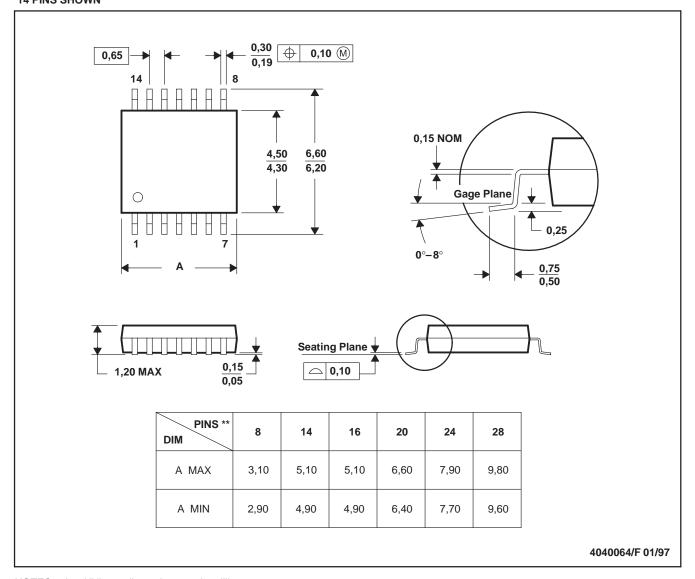
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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